

CEI/CT 31	Materiali antideflagranti
ENV 50269:1997-02	Assessment and representative testing of high-voltage machines
ENV 50269/EC:1997-03	Assessment and representative testing of high-voltage machines
CEI/CT 44	Equipaggiamento elettrico delle macchine industriali
EN 61491:1998-08	Electrical equipment of industrial machines - Serial data link for real-time communication between controls and drives
TS 61496-2:2003-12	Safety of machinery - Electro-sensitive protective equipment Part 2: Particular requirements for equipment using active opto-electronic protective devices (AOPD)
TS 61496-3:2003-12	Safety of machinery - Electro-sensitive protective equipment Part 3: Particular requirements for Active Opto-electronic Protective Devices responsive to Diffuse Reflection (AOPDDR)
CEI/CT 46/48	Cavi simmetrici e coassiali, cordoni, fili, guide d'onda, connettori per radiofrequenza / Componenti elettromeccanici per apparecchiature elettroniche
CECC 299001:1999-04	Technology Approval Schedule: Manufacture of electrical connectors
CEI/CT 46	Cavi simmetrici e coassiali, cordoni, fili, guide d'onda, connettori per radiofrequenza
EN 60154-2:1997-07 (+ IEC 60154-2/EC:1981-11)	Flanges for waveguides Part 2: Relevant specifications for flanges for ordinary rectangular waveguides
EN 60154-2/A1:1997-07	Flanges for waveguides Part 2: Relevant specifications for flanges for ordinary rectangular waveguides
EN 61726:2000-03	Cable assemblies, cables, connectors and passive microwave components - Screening attenuation measurement by the reverberation chamber method
EN 62037:1999-11	RF connectors, connector cable assemblies and cables - Intermodulation level measurement
CEI/CT 48	Componenti elettromeccanici per apparecchiature elettroniche
HD 493.3 S2:1993-10	Dimensions of mechanical structures of the 482.6 mm (19 in) series Part 3: Subracks and associated plug-in units
EN 60512-11-1:1999-11	Electromechanical components for electronic equipment - Basic testing procedures and measuring methods Part 11: Climatic tests Section 1: Test 11a - Climatic sequence
EN 60512-11-8:1999-01	Electromechanical components for electronic equipment - Basic testing procedures and measuring methods Part 11: Climatic tests Section 8: Test 11h - Sand and dust
EN 60512-14-7:1998-02	Electromechanical components for electronic equipment - Basic testing procedures and measuring methods Part 14: Sealing tests Section 7: Test 14g: Impacting water
EN 60603-3:1998-02	Connectors for frequencies below 3 MHz for use with printed boards Part 3: Two-part connectors for printed boards having contacts spaced at 2,54 mm (0,100 in) centres and staggered terminations at that same spacing
EN 60603-4:1998-02	Connectors for frequencies below 3 MHz for use with printed boards Part 4: Two-part connectors for printed boards having contacts spaced at 1,91 mm (0,075 in) centres and staggered terminations at that same spacing
EN 60603-5:1998-02	Connectors for frequencies below 3 MHz for use with printed boards Part 5: Edge-socket connectors and two-part connectors for double-sided printed boards with 2,54 mm (0,1 in) spacing
EN 60603-6:1998-02	Connectors for frequencies below 3 MHz for use with printed boards Part 6: Edge-socket connectors and printed-board connectors with 2,54 mm (0,1 in) contact spacing for single or double-sided printed boards of 1,6 mm (0,063 in) nominal thickness
EN 60603-8:1998-02	Connectors for frequencies below 3 MHz for use with printed boards Part 8: Two-part connectors for printed boards, for basic grid of 2,54 mm (0,1 in), with square male contacts of 0,63 mm x 0,63 mm
EN 60603-9:1998-02	Connectors for frequencies below 3 MHz for use with printed boards Part 9: Two-part connectors for printed boards, backpanels and cable connectors, basic grid of 2,54 mm (0,1 in)
EN 60603-10:1998-02	Connectors for frequencies below 3 MHz for use with printed boards Part 10: Two-part connectors for printed boards for basic grid of 2,54 mm (0,1 in), inverted type
EN 60603-12:1998-02	Connectors for frequencies below 3 MHz for use with printed boards Part 12: Detail specification for dimensions, general requirements and tests for a range of sockets designed for use with integrated circuits
EN 60603-13:1998-02	Connectors for frequencies below 3 MHz for use with printed boards Part 13: Detail specification for two-part connectors of assessed quality, for printed boards for basic grid of 2,54 mm (0,1 in), with free connectors for non-accessible insulation displacement terminations (ID)
EN 61076-2:1999-04	Connectors for use in d.c., low-frequency analogue and in digital high-speed data applications Part 2: Circular connectors with assessed quality - Sectional specification

EN 61076-2-001:2001-12	Connectors for electronic equipment Part 2-001: Circular connectors - Blank detail specification
EN 61076-3-001:2000-01	Connectors for use in d.c., low frequency analogue, and digital high speed data applications Part 3-001: Rectangular connectors with assessed quality - Blank detail specification
EN 61076-3-100:2000-01	Connectors for use in d.c., low-frequency analogue and digital high speed data applications Part 3-100: Rectangular connectors with assessed quality Detail specification for a range of shielded connectors with trapezoidal-shaped shells and non-removable ribbon contacts on a 1,27 mm double row
EN 61076-4-101:2001-10 (+ IEC 61076-4-101/Ed:2003-11)	Connectors for electronic equipment Part 4-101: Printed board connectors with assessed quality - Detail specification for two-part connector modules, having a basic grid of 2,0 mm for printed boards and backplanes in accordance with IEC 60917
EN 61076-4-107:2001-10	Connectors for electronic equipment Part 4-107: Printed board connectors with assessed quality - Detail specification for shielded two-part connectors having a basic grid of 2,0 mm, fixed part with solder and press-in terminations for printed boards, free part with non-accessible insulation displacement and crimp terminations
EN 61076-4-113:2003-02	Connectors for electronic equipment - Printed board connectors Part 4-113: Detail specification for two-part connectors having 5 rows with a grid of 2,54 mm for printed boards and backplanes in bus applications
EN 61076-5:2001-10	Connectors for use in DC, low-frequency analogue and digital high-speed data application Part 5: In-line sockets with assessed quality - Sectional Specification
EN 175101-802:1999-11	Detail specification: Two-part connectors for printed boards for high number of contacts with basic grid of 2,54 mm on 3 or 4 rows
EN 175101-809:1999-11	Detail Specification: Two-part connectors for printed boards having a grid of 2,54 mm, short version in compliance with CECC 75 101-801, with assessed quality
EN 175201-804:1999-11	Detail Specification: Circular connectors - Round contacts, size diameter 1,6 mm, threaded coupling
EN 175301-801:1999-11	Detail Specification: High density rectangular connectors, round removable crimp contacts
EN 175301-803:1999-11	Detail Specification: Rectangular connectors Flat contacts, 0,8 mm thickness, locking screw not detachable
CEI/CT 57	Telecomunicazioni associate ai sistemi elettrici di potenza
EN 60870-5-103:1998-02	Telecontrol equipment and systems Part 5: Transmission protocols Section 103: Companion standard for the informative interface of protection equipment
EN 60870-6-701:1998-10	Telecontrol equipment and systems Part 6: Telecontrol protocols compatible with ISO standards and ITU-T recommendations Section 701: Functional profile for providing the TASE.1 application service in end systems
EN 60870-6-702:1998-11	Telecontrol equipment and systems Part 6: Telecontrol protocols compatible with ISO standards and ITU-T recommendations Section 702: Functional profile for providing the TASE.2 application service in end systems
EN 61334-4-512:2002-02	Distribution automation using distribution line carrier systems Part 4-512: Data Communication Protocols -Systems management using profile 61334-5-1 - Management information base (MIB)
CEI/CT 65	Controllo e misura nei processi industriali
R065-001:1999-12	General purpose field communication system Token passing within EN 50170, volume 2
EN 50170:1996-12	General purpose field communication system
EN 50170/A1:2002/A3:2002	General purpose field communication system
EN 50170/A1/EC:2002-08	General purpose field communication system
EN 50170/A2:1999-12	General purpose field communication system
EN 50170/A3:2002-05	General purpose field communication system
EN 50170/A3/EC:2002-08	General purpose field communication system
EN 50254:1998-12	High efficiency communication subsystem for small data packages
EN 61512-1:1999-06	Batch control Part 1: Models and terminology

CEI/CT 69	Macchine elettriche dei veicoli stradali elettrici
ENV 50275-2-4:1998-10	Conductive charging for electric vehicles Part 2-4: Communication protocol between off-board charger and electric vehicle
CEI/CT 82	Sistemi di conversione fotovoltaica dell'energia solare
EN 60904-10:1998-04	Photovoltaic devices Part 10: Methods of linearity measurement
EN 61721:1999-06	Susceptibility of a photovoltaic (PV) module to accidental impact damage (resistance to impact test)
CEI/CT 86	Fibre ottiche
CECC 78005-802:1999-05	Detail Specification Termini set of assessed quality for optical fibres and cables Type LSD-HR
CECC 86305-801:1997-11	Detail Specification: Connector sets of assessed quality for optical fibres and cables - Type MSC-APC 8° untuned
EN 60793-1-20:2002-03	Optical Fibres Part 1-20: Measurement methods and test procedures - Fibre geometry
EN 60793-1-21:2002-03	Optical Fibres Part 1-21: Measurement methods and test procedures - Coating geometry
EN 60793-1-22:2002-03	Optical fibres Part 1-22: Measurement methods and test procedures - Length measurement
EN 60793-1-31:2002-02	Optical fibres Part 1-31: Measurement methods and test procedures - Tensile strength
EN 60793-1-33:2002-04	Optical fibres Part 1-33: Measurement methods and test procedures - Stress corrosion susceptibility
EN 60793-1-34:2002-02	Optical fibres Part 1-34: Measurement methods and test procedures - Fibre curl
EN 60793-1-41:2002-02	Optical fibres Part 1-41: Measurement methods and test procedures - Bandwidth
EN 60793-1-42:2002-02	Optical fibres Part 1-42: Measurement methods and test procedures - Chromatic dispersion
EN 60793-1-43:2002-02	Optical fibres Part 1-43: Measurement methods and test procedures - Numerical aperture
EN 60793-1-44:2002-02	Optical fibres Part 1-44: Measurement methods and test procedures - Cut-off wavelength
EN 60793-1-46:2002-02	Optical fibres Part 1-46: Measurement methods and test procedures - Monitoring of changes in optical transmittance
EN 60793-1-47:2002-02	Optical fibres Part 1-47: Measurement methods and test procedures - Macrobending loss
EN 60793-1-50:2002-02	Optical Fibres Part 1-50: Measurement methods and test procedures - Damp heat (steady state)
EN 60793-1-51:2002-02	Optical fibres Part 1-51: Measurement methods and test procedures - Dry heat
EN 60793-1-52:2002-02	Optical fibres Part 1-52: Measurement methods and test procedures - Change of temperature
EN 60793-1-53:2002-02	Optical fibres Part 1-53: Measurement methods and test procedures - Water immersion
EN 60793-2-10:2002-04	Optical fibres Part 2-10: Product specifications - Sectional specification for category A1 multimode fibres
EN 60793-2-20:2002-04	Optical fibres Part 2-20: Product specifications -Sectional specification for category A2 multimode fibres
EN 60793-2-30:2002-04	Optical fibres Part 2-30: Product specifications - Sectional specification for category A3 multimode fibres
EN 60793-2-40:2002-04	Optical fibres Part 2-40: Product specifications - Sectional specification for category A4 multimode fibres
EN 60793-2-50:2002-04	Optical fibres Part 2-50: Product specifications - Sectional specification for class B single-mode fibres
EN 60794-1-1:2002-02	Optical fibre cables Part 1-1: Generic specification - General
EN 60794-3:2002-03	Optical fibres cables Part 3: Sectional specification - Outdoor cables
EN 60794-3-10:2002-06	Optical fibre cables Part 3-10: Outdoor cables - Family specification for duct and directly buried optical telecommunication cables

EN 60794-3-20:2002-06	Optical fibre cables Part 3-20: Outdoor cables - Family specification for optical self-supporting aerial telecommunication cables
EN 61290-5-3:2002-04	Optical fibre amplifiers - Basic specification Part 5-3: Test methods for reflectance parameters - Reflectance tolerance using an electrical spectrum analyzer
EN 61753-51-3:2002-03	Fibre optic interconnecting devices and passive components performance standard Part 051-3: Single-mode fibre, plug-style fixed attenuators for category U - Uncontrolled environment
EN 61753-52-3:2002-03	Fibre optic interconnecting devices and passive components performance standard Part 052-3: Single-mode fibre, pigtailed-style fixed attenuators for category U - Uncontrolled environment
EN 61977:2002-03	Fibre optic filters -- Part 1: Generic specification
EN 62148-1:2002-04	Fibre optic active components and devices - Package and interface standards Part 1: General and guidance
EN 181103:1997-12	Blank detail specification Fibre optic branching devices Type: Non wavelength selective transmissive star for telecommunication application
EN 181104:1997-12	Blank detail specification Fibre optic branching devices Type: Wavelength selective transmissive star for telecommunication application
EN 186150:1997-05	Sectional Specification Connector sets for optical fibres and cables Type OCCA BU
EN 186160:1997-05	Sectional Specification Connector sets for optical fibres and cables Type OCCA PC
EN 186170:1998-02	Sectional Specification Connector sets for optical fibres and cables Type RCC
EN 186300:1999-02	Sectional Specification Connector sets for optical fibres and cables Type MSC
EN 187105:2002-05	Single mode optical cable (duct /direct buried installation)
CEI/CT 94	Relè elettrici a tutto o niente (ex CT 94/95, ex CT 41)
CECC 16207-804:1999-09	Detail Specification: All-or-nothing relays for severe airborne environmental conditions 1/10 size crystal can, monostable polarized, 2 change-over contacts (2PDT), 0,5 A
CECC 16207-805:1999-09	Detail Specification: All-or-nothing relays for severe airborne environmental conditions TO 5, monostable non polarized, 2 change-over contacts (2PDT), 1 A
CECC 16303-801:1999-09	Detail Specification: Electromechanical all-or-nothing heavy load relays 1/2 cubic inch, monostable, 2 change-over (DPDT), 10A
CECC 16303-802:1999-09	Detail Specification: Electromechanical all-or-nothing heavy load relays 1 cubic inch, monostable, 4 change-over (4PDT), 10A
CECC 16303-803/A1:1998-03 (*)	Detail Specification: Electromechanical all-or-nothing heavy load relays 2/10 cubic inch, monostable, 2 change-over (DPDT), 5A
CECC 16303-804/A1:1998-03 (*)	Detail Specification: Electromechanical all-or-nothing heavy load relays 4/10 cubic inch, monostable, 4 change-over (4PDT), 5 A
CECC 16303-805/A1:1998-03 (*)	Detail Specification: Electromechanical all-or-nothing heavy load relays 1 cubic inch, monostable, 3 change-over (3PDT), 25A
CECC 16303-806/A1:1998-03 (*)	Detail Specification: Electromechanical all-or-nothing heavy load relays 2,5 cubic inch, monostable, 6 change-over (6PDT), 10 A
CECC 16303-807/A1:1998-03 (*)	Detail Specification: Electromechanical all-or-nothing heavy load relays 4/10 cubic inch, monostable, 3 change-over (3PDT), 10 A
CECC 16303-808/A1:1998-03 (*)	Detail Specification: Electromechanical all-or-nothing heavy load relays 2/10 cubic inch, monostable,1 change-over (1PDT), 10 A
CECC 16303-809/A1:1998-03 (*)	Detail Specification: Electromechanical all-or-nothing heavy load relays 1/2 cubic inch, monostable,1 change-over (1PDT), 25 A
CECC 16303-810:1999-09	Detail Specification: Electromechanical all-or-nothing heavy load relays 1/2 cubic inch, bistable (magnetic latching), 2 change-over (DPDT), 10A

CEI/CT 100	Sistemi e apparecchiature audio, video e multimediali (ex CT 84/60, SC 12A, SC 12G)
-------------------	--

EN 50203:1996-12	Automatic channel installations (ACI)
EN 50203/A1:1997-02	Automatic channel installation (ACI)
EN 60094-2:1995-01 (+ IEC 60094-2/Ec:1995-03)	Magnetic tape sound recording and reproducing systems - Part 2: Calibration tapes
EN 60094-4/A1:1994-08	Magnetic tape sound recording and reproducing systems Part 4: Mechanical magnetic tape properties
<i>Per la Norma base cui la presente modifica si riferisce si veda la CEI EN 60094-4:1998 (CEI 60-21) nella Sezione "Norme CEI in vigore - Indice progressivo per CT" o nella Sezione "Indice Norme e Pubblicazioni Europee recepite dal CEI"</i>	
EN 60094-5/A1:1996-03	Magnetic tape sound recording and reproducing systems Part 5: Electrical magnetic tape properties
<i>Per la Norma base cui il presente Amendment si riferisce si veda la CEI EN 60094-5:1998 (CEI 60-22) nella Sezione "Norme CEI in vigore - Indice progressivo per CT" o nella Sezione "Indice Norme e Pubblicazioni Europee recepite dal CEI"</i>	
EN 60094-7/A1:1996-03	Magnetic tape sound recording and reproducing systems Part 7: Cassette for commercial tape records and domestic use
<i>Per la Norma base cui il presente Amendment si riferisce si veda la CEI EN 60094-7:1998 (CEI 60-28) nella Sezione "Norme CEI in vigore - Indice progressivo per CT" o nella Sezione "Indice Norme e Pubblicazioni Europee recepite dal CEI"</i>	
EN 60268-7:1996-05	Sound system equipment Part 7: Headphones and earphones
EN 60268-12/A2:1995-02	Sound system equipment Part 12: Application of connectors for broadcast and similar use
<i>Per la Norma base cui il presente Amendment si riferisce si veda la CEI EN 60268-12:1998 (CEI 84-12) nella Sezione "Norme CEI in vigore - Indice progressivo per CT" o nella Sezione "Indice Norme e Pubblicazioni Europee recepite dal CEI"</i>	
EN 60315-3:1999-04	Methods of measurement on radio receivers for various classes of emission Part 3: Receivers for amplitude-modulated sound-broadcasting emissions
EN 60315-3/A1:1999-04	Methods of measurement on radio receivers for various classes of emission Part 3: Receivers for amplitude-modulated sound-broadcasting emissions
EN 60315-9:1996-07	Methods of measurement on radio receivers for various classes of emission Part 9: Measurement of the characteristics relevant to radio data system (RDS) reception
EN 60574-21:1993-12	Audiovisual, video and television equipment and systems Part 21: Video tape leader and trailer for education and training applications
EN 60843-1:1994-04	Helican-Scan video tape cassette system using 8 mm magnetic tape - 8 mm Video Part 1: General specifications
EN 60843-2:1995-06	Helical-scan video tape cassette system using 8 mm magnetic tape - 8 mm Video Part 2: PCM multi-track audio system
EN 60843-4:2000-04	Helical-scan video tape cassette system using 8 mm magnetic tape (8 mm video) Part 4: Video subcode - VSC
EN 60908:1999-03	Audio recording - Compact disc digital audio system
EN 61096/A1:1996-12	Methods of measuring the characteristics of reproducing equipment for digital audio compact discs
<i>Per la Norma base cui il presente Amendment si riferisce si veda la CEI EN 61096:1998 (CEI 60-41) nella Sezione "Norme CEI in vigore - Indice progressivo per CT" o nella Sezione "Indice Norme e Pubblicazioni Europee recepite dal CEI"</i>	
EN 61105:1993-10	Reference tapes for video tape recorder systems
EN 61119-2:1994-07	Digital audio tape cassette system (DAT) Part 2: DAT calibration tape
EN 61119-3:1994-07	Digital audio tape cassette system (DAT) Part 3: DAT tape properties
EN 61119-5:1995-01	Digital audio tape cassette system (DAT) Part 5: DAT for professional use
EN 61119-6:1994-07	Digital audio tape cassette system (DAT) Part 6: Serial copy management system
EN 61120-3:1993-10	Digital audio tape recorder reel to reel system, using 6.3 mm magnetic tape, for professional use Part 3: Format B
EN 61146-1:1996-09	Video cameras (PAL/SECAM/NTSC) - Methods of measurement Part 1: Non-broadcast single-sensor cameras
EN 61213:1994-01	Analogue audio recording on video tape - Polarity of magnetization
EN 61237-2:1995-06	Broadcast video tape recorders - Methods of measurement Part 2: Electrical measurements of analogue composite video signals
EN 61319-1:1996-01	Interconnections of satellite receiving equipment Part 1: Europe

EN 61319-1/A11:1999-04	Interconnections of satellite receiving equipment Part 1: Europe
EN 61834-1:1998-10	Helical-scan digital video cassette recording system using 6,35 mm magnetic tape for consumer use (525-60, 625-50, 1125-60 and 1250-50 systems) Part 1: General specifications
EN 61834-1/A1:2001-07	Recording - Helical-scan digital video cassette recording system using 6,35 mm magnetic tape for consumer use (525-60, 625-50, 1125-60 and 1250-50 systems) Part 1: General specifications
EN 61834-2:1998-10	Recording - Helical-scan digital video cassette recording system using 6,35 mm magnetic tape for consumer use (525-60, 625-50, 1125-60 and 1250-50 systems) Part 2: SD format for 525-60 and 625-50 systems
EN 61834-3:2000-03	Recording - Helical-scan digital video cassette recording system using 6,35 mm magnetic tape for consumer use (525-60, 625-50, 1125-60 and 1250-50 systems) Part 3: HD format for 1125-60 and 1250-50 systems
EN 61834-4:1998-08	Recording - Helical-scan digital video cassette recording system using 6,35 mm magnetic tape for consumer use (525-60, 625-50, 1125-60 and 1250-50 systems) Part 4: Packheader table and the contents
EN 61834-5:1998-10	Recording - Helical-scan digital video cassette recording system using 6,35 mm magnetic tape for consumer use (525-60, 625-50, 1125-60 and 1250-50 systems) Part 5: The character information system
EN 61834-6:2000-11	Recording - Helical-scan digital video cassette recording system using 6,35 mm magnetic tape for consumer use (525-60, 625-50, 1125-60 and 1250-50 systems) Part 6: SDL format
EN 61834-7:2001-06	Recording - Helical-scan digital video cassette recording system using 6,35 mm magnetic tape for consumer use (525-60, 625-50, 1125-60 and 1250-50 systems) Part 7: EDTV2 format
EN 61834-8:2001-09	Recording - Helical-scan digital video cassette recording system using 6,35 mm magnetic tape for consumer use (525-60, 625-50, 1125-60 and 1250-50 systems) Part 8: PALplus format for 625-50 system
EN 61834-9:2001-07	Recording - Helical-scan digital video cassette recording system using 6,35 mm magnetic tape for consumer use (525-60, 625-50, 1125-60 and 1250-50 systems) Part 9: DVB format
EN 61834-10:2001-05 (+ IEC 61834-10/Ec1:2001-06)	Recording - Helical-scan digital video cassette recording system using 6,35 mm magnetic tape for consumer use (525-60, 625-50, 1125-60 and 1250-50 systems) Part 10: DTV format
EN 61883-7:2003-04	Consumer audio/video equipment - Digital interface Part 7: Transmission of ITU-R BO.1294 System B
EN 61904:2000-09	Video recording - Helical-scan digital video cassette recording format using 12,65 mm magnetic tape and incorporating data compression (Format Digital-L)
EN 62071:2001-03	Helical-scan compressed digital video cassette recording system using 6,35 mm magnetic tape - Format D-7
EN 62105:2002	Digital audiobroadcast system - Specification of the receiver data interface (RDI)
<i>La presente Norma sostituisce la EN 50255:1997.</i>	
EN 62106:2001-12	Specification of the radio data system (RDS) for VHF/FM sound broadcasting in the frequency range from 87,5 to 108,0 MHz
EN 62121:2001-12	Methods of measurement for minidisc recorders /players
EN 62156:2001-12	Digital video recording with video compression 12,65 mm Type D-9 component format 525/60 and 625/50 (DIGITAL S)
EN 62289:2003-08	Video recording - Helical-scan digital video cassette recording format using 12,65 mm magnetic tape and incorporating MPEG-2 compression - Format D-10
CEI/CT 101	Elettrostatica
EN 61340-3-1:2002-06	Electrostatics Part 3-1: Methods for simulation of electrostatic effects - Human body model (HBM) - Component testing
EN 61340-3-2:2002-06	Electrostatics Part 3-2: Methods for simulation of electrostatic effects - Machine model (MM) - Component testing

CEI/CT 103	Radiotrasmissioni (ex SC 103)
EN 60835-2-11:1997-01	Methods of measurement for equipment used in digital microwave radio transmission systems Part 2: Measurements on terrestrial radio-relay systems Section 11: Cross-polarization interference canceller
EN 60835-3-13:1996-07	Methods of measurement for equipment used in digital microwave radio transmission systems Part 3: measurements on satellite earth stations Section 13: VSAT systems
EN 60835-3-14:1996-07	Methods of measurement for equipment used in digital microwave radio transmission systems Part 3: measurements on satellite earth stations Section 14: Earth stations for satellite news gathering (SNG)
EN 60835-3-6:1996-07	Methods of measurement for equipment used in digital microwave radio transmission systems Part 2: Measurements on terrestrial radio-relay systems Section 6: High power amplifiers
CEI/CT 205	Sistemi bus per edifici (ex CT 83)
R205-008:1996-10	Home and Building Electronic Systems (HBES) Technical Report 8: Transport Layer and Network Layer, Class 1
R205-007:1996-10	Home and Building Electronic Systems (HBES) Technical Report 7: Aspects of application - Application Layer
R205-009:1996-10	Home and Building Electronic Systems (HBES) Technical Report 9: Media and media dependent layers - Network based on Twisted Pair, Class 1
R205-010:1996-10	Home and Building Electronic Systems (HBES) Technical Report 10: Interfaces - Medium Interface, Twisted Pair, Class 1
R205-011:1996-10	Home and Building Electronic Systems (HBES) Technical Report 11: Management
CEI/CT 309	Componentistica elettronica (ex CT 40, 47, 52/91)
EN 60431:1997-04 + A2:1998	Dimensions of square cores (RM-cores) made of magnetic oxides and associated parts
EN 61185:1997-05	Magnetic oxide cores (ETD-cores) intended for use in power supply applications - Dimensions
CECC 23100-801:1998-02	Capability Detail Specification: Single and double-sided printed boards with plain holes
CECC 23200-801:1998-02	Capability Detail Specification: Single and double-sided printed boards with plated-through holes
CECC 23300-801:1998-02	Capability Detail Specification: Multi-layer printed boards
CECC 32101-804:2001-05	Detail specification: Fixed multilayer ceramic surface mounting capacitors, class 1, sub-class 1B, type CG, climatic category 55/125/56, assessment level EZ, with failure rate levels
CECC 32101-805:2001-05	Detail specification: Fixed multilayer ceramic surface mounting capacitors, class 2, sub-classes 2C1 and 2R1, climatic category 55/125/56, assessment level EZ, with failure rate levels
CECC 40101-806:1997-07	Detail Specification: Fixed low power non-wirewound resistors - Stability classes 0,5; 1; 2
CECC 40201-801:1998-05	Detail specification: Fixed power resistors - Wirewound vitreous enamel - Stability class 5
CECC 40402-801:2000-02	Detail Specification: Fixed low power wire wound surface mounting (SMD) resistors
CECC 265001:1998-09	Technology Approval Schedule: Film and hybrid integrated circuits
EN 60115-1:2001-09	Fixed resistors for use in electronic equipment Part 1: Generic specification
EN 60115-1/A1:2001-09	Fixed resistors for use in electronic equipment Part 1: Generic specification
EN 60122-1:2002-12	Quartz crystal units of assessed quality Part 1: Generic specification
EN 60122-3:2001-10	Quartz crystal units of assessed quality Part 3: Standard outlines and lead connections
EN 60133:2001-03	Dimensions of pot-cores made of magnetic oxides and associated parts
EN 60139:2001-03	Preparation of outline drawings for cathode-ray tubes, their components, connections and gauges
EN 60191-3:1999-11	Mechanical standardization of semiconductor devices Part 3: General rules for the preparation of outline drawings of integrated circuits
EN 60191-4:1999-10	Mechanical standardization of semiconductor devices Part 4: Coding system and classification into forms of package outlines for semiconductor device packages
EN 60191-4/A1:2002-02	Mechanical standardization of semiconductor devices Part 4: Coding system and classification into forms of package outlines for semiconductor device packages
EN 60191-4/A2:2002-10	Mechanical standardization of semiconductor devices Part 4: Coding system and classification into forms of package outlines for semiconductor device packages

EN 60191-6-12:2002-07	Mechanical standardization of semiconductor devices Part 6-12: General rules for the preparation of outline drawings of surface mounted semiconductor device packages - Design guide for fine-pitch land grid array (FLGA) - Rectangular type
EN 60191-6-2:2002-02	Mechanical standardization of semiconductor devices Part 6-2: General rules for the preparation of outline drawings of surface mounted semiconductor device packages - Unit design guide for 1,50 mm, 1,27 mm and 1,00 mm pitch ball and column terminal packages
EN 60191-6-3:2000-12	Mechanical standardization of semiconductor devices Part 6-3: General rules for the preparation of outline drawings of surface mounted semiconductor device packages - Measuring methods for package dimensions of quad flat packs (QFP)
EN 60191-6-4:2003-07	Mechanical standardization of semiconductor devices Part 6-4: General rules for the preparation of outline drawings of surface mounted semiconductor device packages - Measuring methods for package dimensions of ball grid array (BGA)
EN 60191-6-5:2001-10	Mechanical standardization of semiconductor devices Part 6-5: General rules for the preparation of outline drawings of surface mounted semiconductor device packages - Design guide for fine-pitch ball grid array (FBGA)
EN 60191-6-6:2001-07	Mechanical standardization of semiconductor devices Part 6-6: General rules for the preparation of outline drawings of surface mounted semiconductor device packages - Design guide for fine pitch land grid array (FLGA)
EN 60191-6-8:2001-10	Mechanical standardization of semiconductor devices Part 6-8: General rules for the preparation of outline drawings of surface mounted semiconductor device packages - Design guide for glass sealed ceramic quad flatpack (G-QFP)
EN 60205:2001-06 (+ IEC 60205/Ec:2002-11)	Calculation of the effective parameters of magnetic piece parts
EN 60249-1/A4:1994-01	Base materials for printed circuits Part 1: Test methods
EN 60249-1/A4 Ec:1994-03	Base material for printed circuits Part 1: Test methods
EN 60249-2-1/A3:1995-10	Base materials for printed circuits Part 2: Specifications Specification No. 1: Phenolic cellulose paper copper-clad laminated sheet, high electrical quality
<i>Per la Norma base cui il presente Amendment si riferisce si veda la CEI EN 60249-2-1:1996 (CEI 52-12) nella Sezione "Norme CEI in vigore - Indice progressivo per CT" o nella Sezione "Indice Norme e Pubblicazioni Europee recepite dal CEI"</i>	
EN 60249-2-1/A4:2000-04	Base materials for printed circuits Part 2: Specifications Specification No. 1: Phenolic cellulose paper copper-clad laminated sheet, high electrical quality
<i>Per la Norma base cui il presente Amendment si riferisce si veda la CEI EN 60249-2-1:1996 (CEI 52-12) nella Sezione "Norme CEI in vigore - Indice progressivo per CT" o nella Sezione "Indice Norme e Pubblicazioni Europee recepite dal CEI"</i>	
EN 60249-2-11/A2:1994-03	Base materials for printed circuits Part 2: Specifications Specification No. 11: Thin epoxide woven glass fabric copper-clad laminated sheet, general purpose grade for use in the fabrication of multilayer printed boards
EN 60249-2-11/A3:1995-11	Base materials for printed circuits Part 2: Specifications Specification No. 11: Thin epoxide woven glass fabric copper-clad laminated sheet, general purpose grade for use in the fabrication of multilayer printed boards
EN 60249-2-11/A4:2000-11	Base materials for printed circuits Part 2: Specifications Specification No. 11: Thin epoxide woven glass fabric copper-clad laminated sheet, general purpose grade, for use in the fabrication of multilayer printed boards
EN 60249-2-12:1994-03	Base materials for printed circuits Part 2: Specifications Specification No. 12: Thin epoxide woven glass fabric copper-clad laminated sheet of defined flammability, for use in the fabrication of multilayer printed boards
EN 60249-2-12/A2:1994-03	Base materials for printed circuits Part 2: Specifications Specification No. 12: Thin epoxide woven glass fabric copper-clad laminated sheet of defined flammability, for use in the fabrication of multilayer printed boards
EN 60249-2-12/A3:1995-11	Base materials for printed circuits Part 2: Specifications Specification No. 12: Thin epoxide woven glass fabric copper-clad laminated sheet of defined flammability, for use in the fabrication of multilayer printed boards
EN 60249-2-12/A4:2000-11	Base materials for printed circuits Part 2-12: Specifications: thin epoxide woven glass fabric copper-clad laminated sheet of defined flammability, for use in the fabrication of multilayer printed boards
EN 60249-2-13:1994-03	Base materials for printed circuits Part 2: Specifications Specification No. 13: Flexible copper-clad laminated polyimide film, general purpose grade

EN 60249-2-13/A1:1994-03	Base materials for printed circuits Part 2: Specifications Specification No. 13: Flexible copper-clad laminated polyimide film, general purpose grade
EN 60249-2-14:1994-03	Base materials for printed circuits Part 2: Specifications Specification No. 14: Phenolic cellulose paper copper-clad laminated sheet of defined flammability (vertical burning test), economic quality
EN 60249-2-14/A3:1994-03	Base materials for printed circuits Part 2: Specifications Specification No. 14: Phenolic cellulose paper copper-clad laminated sheet of defined flammability (vertical burning test), economic quality
EN 60249-2-14/A4:1995-11	Base materials for printed circuits Part 2: Specifications Specification No. 14: Phenolic cellulose paper copper-clad laminated sheet of defined flammability (vertical burning test), economic quality
EN 60249-2-14/A5:2000-11	Base materials for printed circuits Part 2: Specifications Specification No. 14: Phenolic cellulose paper copper-clad laminated sheet of defined flammability (vertical burning test), economic quality
EN 60249-2-2/A3:1994-02	Base materials for printed circuits Part 2: Specifications Specification No. 2: Phenolic cellulose paper copper-clad laminated sheet, economic quality
EN 60249-2-2/A4:1995-10	Base materials for printed circuits Part 2: Specifications Specification No. 2: Phenolic cellulose paper copper-clad laminated sheet, economic quality
EN 60249-2-2/A5:2000-04	Base materials for printed circuits Part 2: Specifications Specification No. 2: Phenolic cellulose paper copper-clad laminated sheet, economic quality
EN 60249-2-2/EC:1994-03	Base materials for printed circuits Part 2: Specifications Specification No. 2: Phenolic cellulose paper copper-clad laminated sheet, economic quality
EN 60249-2-3/A2:1994-02	Base materials for printed circuits Part 2: Specifications Specification No. 3: Epoxide cellulose paper copper-clad laminated sheet of defined flammability (vertical burning test)
EN 60249-2-3/A2/EC:1994-03	Base materials for printed circuits Part 2: Specifications Specification No. 3: Epoxide cellulose paper copper-clad laminated sheet of defined flammability (vertical burning test)
EN 60249-2-3/A3:1995-10	Base materials for printed circuits Part 2: Specifications Specification No. 3: Epoxide cellulose paper copper-clad laminated sheet of defined flammability (vertical burning test)
EN 60249-2-3/A4:2000-04	Base materials for printed circuits Part 2: Specifications Specification No. 3: Epoxide cellulose paper copper-clad laminated sheet of defined flammability (vertical burning test)
EN 60249-2-3/EC:1994-03	Base materials for printed circuits Part 2: Specifications Specification No. 3: Epoxide cellulose paper copper-clad laminated sheet of defined flammability (vertical burning test)
EN 60249-2-4/A3:1994-02	Base materials for printed circuits Part 2: Specifications Specification No. 4: Epoxide woven glass fabric copper-clad laminated sheet, general purpose grade
EN 60249-2-4/A3/EC:1994-03	Base materials for printed circuits Part 2: Specifications Specification No. 4: Epoxide woven glass fabric copper-clad laminated sheet, general purpose grade
EN 60249-2-4/A4:1995-10	Base materials for printed circuits Part 2: Specifications Specification No. 4: Epoxide woven glass fabric copper-clad laminated sheet, general purpose grade
EN 60249-2-4/A5:2000-04	Base materials for printed circuits Part 2: Specifications Specification No. 4: Epoxide woven glass fabric copper-clad laminated sheet, general purpose grade
EN 60249-2-4/EC:1994-03	Base materials for printed circuits Part 2: Specifications Specification No. 4: Epoxide woven glass fabric copper-clad laminated sheet, general purpose grade
EN 60249-2-5/A3:1994-02	Base materials for printed circuits Part 2: Specifications Specification No. 5: Epoxide woven glass fabric copper-clad laminated sheet of defined flammability (vertical burning test)
EN 60249-2-5/A3/EC:1994-03	Base materials for printed circuits Part 2: Specifications Specification No. 5: Epoxide woven glass fabric copper-clad laminated sheet of defined flammability (vertical burning test)
EN 60249-2-5/A4:1995-10	Base materials for printed circuits Part 2: Specifications Specification No. 5: Epoxide woven glass fabric copper-clad laminated sheet of defined flammability (vertical burning test)

EN 60249-2-5/A5:2000-11	Base materials for printed circuits Part 2: Specifications Specification No. 5: Epoxide woven glass fabric copper-clad laminated sheet of defined flammability (vertical burning test)
EN 60249-2-5/EC:1994-03	Base materials for printed circuits Part 2: Specifications Specification No. 5: Epoxide woven glass fabric copper-clad laminated sheet of defined flammability (vertical burning test)
EN 60249-2-6/A2:1994-02	Base materials for printed circuits Part 2: Specifications Specification No. 6: Phenolic cellulose paper copper-clad laminated sheet of defined flammability (horizontal burning test)
EN 60249-2-6/A2/EC:1994-03	Base materials for printed circuits Part 2: Specifications Specification No. 6: Phenolic cellulose paper copper-clad laminated sheet of defined flammability (horizontal burning test)
EN 60249-2-6/A3:1995-10	Base materials for printed circuits Part 2: Specifications Specification No. 6: Phenolic cellulose paper copper-clad laminated sheet of defined flammability (horizontal burning test)
EN 60249-2-6/A4:2000-11	Base materials for printed circuits Part 2: Specifications Specification No. 6: Phenolic cellulose paper copper-clad laminated sheet of defined flammability (horizontal burning test)
EN 60249-2-6/EC:1994-03	Base materials for printed circuits Part 2: Specifications Specification No. 6: Phenolic cellulose paper copper-clad laminated sheet of defined flammability (horizontal burning test)
EN 60249-2-7/A2:1994-02	Base materials for printed circuits Part 2: Specifications Specification No. 7: Phenolic cellulose paper copper-clad laminated sheet of defined flammability (vertical burning test)
EN 60249-2-7/A2/EC:1994-03	Base materials for printed circuits Part 2: Specifications Specification No. 7: Phenolic cellulose paper copper-clad laminated sheet of defined flammability (vertical burning test)
EN 60249-2-7/A3:1995-10	Base materials for printed circuits Part 2: Specifications Specification No. 7: Phenolic cellulose paper copper-clad laminated sheet of defined flammability (vertical burning test)
EN 60249-2-7/A4:2000-11	Base materials for printed circuits Part 2: Specifications Specification No. 7: Phenolic cellulose paper copper-clad laminated sheet of defined flammability (vertical burning test)
EN 60249-2-7/EC:1994-03	Base materials for printed circuits Part 2: Specifications Specification No. 7: Phenolic cellulose paper copper-clad laminated sheet of defined flammability (vertical burning test)
EN 60286-5:1997-04	Packaging of components for automatic handling Part 5: Matrix trays
EN 60368-1:2000-04	Piezoelectric filters of assessed quality Part 1: Generic specification
EN 60368-1/EC:2001-02	Piezoelectric filters of assessed quality Part 1: Generic specification
EN 60368-2-2:1999-02	Piezoelectric filters Part 2: Guide to the use of piezoelectric filters Section 2: Piezoelectric ceramic filters
EN 60368-3:2001-10	Piezoelectric filters of assessed quality Part 3: Standard outlines and lead connections
EN 60368-4:2000-12	Piezoelectric filters of assessed quality Part 4: Sectional specification - Capability approval
EN 60368-4/EC:2001-02	Piezoelectric filters of assessed quality Part 4: Sectional specification - Capability approval
EN 60368-4-1:2000-12	Piezoelectric filters of assessed quality Part 4-1: Blank detail specification - Capability approval
EN 60368-4-1/EC:2001-02	Piezoelectric filters of assessed quality Part 4-1: Blank detail specification - Capability approval
EN 60384-20:1999-02	Fixed capacitors for use in electronic equipment Part 20: Sectional specification: Fixed metallized polyphenylene sulfide film dielectric surface mount d.c. capacitors
EN 60384-20-1:1999-02	Fixed capacitors for use in electronic equipment Part 20: Blank detail specification: Fixed metallized polyphenylene sulfide film dielectric surface mount d.c. capacitors - Assessment level EZ
EN 60401-2:2003-06	Terms and nomenclature for cores made of magnetically soft ferrites Part 2: Reference of dimensions
EN 60401-3:2003-12	Terms and nomenclature for cores made of magnetically soft ferrites Part 3: Guide on the format of data appearing in manufacturer's catalogues of transformer and inductor cores
EN 60424-1:1999-08	Ferrite cores - Guide on the limits of surface irregularities Part 1: General specification
EN 60424-2:1997-10	Guidance of the limits of surface irregularities of ferrite cores Part 2: RM-cores

EN 60424-3:1999-08	Ferrite cores - Guide on the limits of surface irregularities Part 3: ETD-cores and E-cores
EN 60424-4:2001-05	Ferrite cores - Guide on the limits of surface irregularities Part 4: Ring cores
EN 60431/A2:1998-08	Dimensions of square cores (RM-cores) made of magnetic oxides and associated parts
EN 60444-1:1997-04	Measurement of quartz crystal unit parameters by zero phase technique in a pi-network Part 1: Basic method for the measurement of resonance frequency and resonance resistance of quartz crystal units by zero phase technique in a pi-network
EN 60444-1/A1:1999-10	Measurement of quartz crystal unit parameters by zero phase technique in a pi-network Part 1: Basic method for the measurement of resonance frequency and resonance resistance of quartz crystal units by zero phase technique in a pi-network
EN 60444-2:1997-04	Measurement of quartz crystal unit parameters by zero phase technique in a pi-network Part 2: Phase offset method for measurement of motional capacitance of quartz crystal units
EN 60444-3:1997-04	Measurement of quartz crystal unit parameters by zero phase technique in a pi-network Part 3: Basic method for the measurement of two terminal parameters of quartz crystal units up to 200 MHz by phase technique in a pi-network with compensation of the parallel capacitance C_0
EN 60444-4:1997-04	Measurement of quartz crystal unit parameters by zero phase technique in a pi-network Part 4: Method for the measurement of the load resonance frequency f_L , load resonance resistance R_L and the calculation of other derived values of quartz crystal units, up to 30 MHz
EN 60444-5:1997-04	Measurement of quartz crystal unit parameters Part 5: Methods for the determination of equivalent electrical parameters using automatic network analyzer techniques and error correction
EN 60444-6:1997-04	Measurement of quartz crystal unit parameters Part 6: Measurement of drive level dependence (DLD)
EN 60444-8:2003-10	Measurement of quartz crystal unit parameters Part 8: Test fixture for surface mounted quartz crystal units
EN 60679-1:1998-02	Quartz crystal controlled oscillators of assessed quality Part 1: Generic specification
EN 60679-1/A1:2002-03	Quartz crystal controlled oscillators of assessed quality Part 1: Generic specification
EN 60679-3:2001-10	Quartz crystal controlled oscillators of assessed quality Part 3: Standard outlines and lead connections
EN 60679-4:1998-02	Quartz crystal controlled oscillators of assessed quality Part 4: Sectional Specification - Capability approval
EN 60679-4-1:1998-04	Quartz crystal controlled oscillators of assessed quality Part 4-1: Blank detail specification - Capability approval
EN 60679-5:1998-08	Quartz crystal controlled oscillators of assessed quality Part 5: Sectional specification - Qualification approval
EN 60679-5-1:1998-08	Quartz crystal controlled oscillators of assessed quality Part 5-1: Blank detail specification - Qualification approval
EN 60738-1:1999-01	Thermistors - Directly heated positive step-function temperature coefficient Part 1: Generic specification
EN 60738-1-1:1999-01	Thermistors - Directly heated positive step-function temperature coefficient Part 1-1: Blank detail specification - Current limiting application - Assessment level EZ
EN 60738-1-2:1999-01	Thermistors - Directly heated positive step-function temperature coefficient Part 1-2: Blank detail specification - Heating element application - Assessment level EZ
EN 60738-1-3:1999-01	Thermistors - Directly heated positive step-function temperature coefficient Part 1-3: Blank detail specification - Inrush current application - Assessment level EZ
EN 60738-1-4:1999-01	Thermistors - Directly heated positive step-function temperature coefficient Part 1-4: Blank detail specification - Sensing application - Assessment level EZ
EN 60747-5-1:2001-07	Discrete semiconductor devices and integrated circuits Part 5-1: Optoelectronic devices - General
EN 60747-5-1/A1:2002-02	Discrete semiconductor devices and integrated circuits Part 5-1: Optoelectronic devices - General
EN 60747-5-1/A2:2002-05	Discrete semiconductor devices and integrated circuits Part 5-1: Optoelectronic devices - General
EN 60747-5-2:2001-07	Discrete semiconductor devices and integrated circuits Part 5-2: Optoelectronic devices - Essential ratings and characteristics
EN 60747-5-2/A1:2002-05	Discrete semiconductor devices and integrated circuits Part 5-2: Optoelectronic devices - Essential ratings and characteristics
EN 60747-5-3:2001-07	Discrete semiconductor devices and integrated circuits Part 5-3: Optoelectronic devices - Measuring methods
EN 60747-5-3/A1:2002-05	Discrete semiconductor devices and integrated circuits Part 5-3: Optoelectronic devices - Measuring methods
EN 60747-16-1:2002-02	Semiconductor devices Part 16-1: Microwave integrated circuits - Amplifiers

EN 60747-16-3:2002-07	Semiconductor devices Part 16-3: Microwave integrated circuits - Frequency converters
EN 60852-4:1996-08	Outline dimensions of transformers and inductors for use in telecommunication and electronic equipment Part 4: Transformers and inductors using YUI-2 laminations
EN 60862-2:2002-09	Surface acoustic wave (SAW) filters of assessed quality Part 2: Guidance on use
EN 60862-3:2003-12	Surface acoustic wave (SAW) filters of assessed quality Part 3: Standard outlines
EN 60938-1:1999-12	Fixed inductors for electromagnetic interference suppression Part 1: Generic specification
EN 60938-2:1999-12	Fixed inductors for electromagnetic interference suppression Part 2: Sectional specification
EN 60938-2-1:1999-12	Fixed inductors for electromagnetic interference suppression Part 2-1: Blank detail specification - Inductors for which safety tests are required - Assessment level D
EN 60938-2-2:1999-12	Fixed inductors for electromagnetic interference suppression Part 2-2: Blank detail specification - Inductors for which safety tests are required (only)
EN 61007:1997-05	Transformers and inductors for use in electronic and telecommunication equipment - Measuring methods and test procedures
EN 61019-2:1997-08	Surface acoustic wave (SAW) resonators Part 2: Guide to the use
EN 61021-1:1997-04	Laminated core packages for transformers and inductors used in telecommunication and electronic equipment Part 1: Dimensions
EN 61021-2:1997-04	Laminated core packages for transformers and inductors for use in telecommunication and electronic equipment Part 2: Electrical characteristics for cores using YEE 2 laminations
EN 61188-1-1:1997-10	Printed boards and assemblies - Design and use Part 1: Generic requirements Section 1: Flatness considerations for electronic assemblies
EN 61189-1:1997-04	Test methods for electrical materials, printed boards and interconnection structures and assemblies Part 1: General test methods and methodology
EN 61189-1/A1:2001-10	Test methods for electrical materials, printed boards and other interconnection structures and assemblies Part 1: General test methods and methodology
EN 61189-2:1997-04	Test methods for electrical materials, printed boards and other interconnection structures and assemblies Part 2: Test methods for materials for interconnection structures
EN 61189-2/A1:2000-05	Test methods for electrical materials, interconnection structures and assemblies Part 2: Test methods for materials for interconnection structures
EN 61189-2/Ed:1997-08	Test methods for electrical materials, printed boards and other interconnection structures and assemblies Part 2: Test methods for materials for interconnection structures
EN 61189-3:1997-04	Test methods for electrical materials, interconnection structures and assemblies Part 3: Test methods for interconnection structures (printed boards)
EN 61189-3/A1:1999-09	Test methods for electrical materials, interconnection structures and assemblies Part 3: Test methods for interconnection structures (printed boards)
EN 61240:1997-04	Piezoelectric devices - Preparation of outline drawings of surface-mounted devices (SMD) for frequency control and selection - General rules
EN 61247:1997-05	PM cores made of magnetic oxides and associated parts - Dimensions
EN 61248-1:1997-08	Transformers and inductors for use in electronic and telecommunication equipment Part 1: Generic specification
EN 61248-2:1997-08	Transformers and inductors for use in electronic and telecommunication equipment Part 2: Sectional specification for signal transformers on the basis of the capability approval procedure
EN 61248-3:1997-08	Transformers and inductors for use in electronic and telecommunication equipment Part 3: Sectional specification for power transformers on the basis of the capability approval procedure
EN 61248-4:1997-08	Transformers and inductors for use in electronic and telecommunication equipment Part 4: Sectional specification for power transformers for switched mode power supplies (SMPS) on the basis of the capability approval procedure
EN 61248-5:1997-08	Transformers and inductors for use in electronic and telecommunication equipment Part 5: Sectional specification for pulse transformers on the basis of the capability approval procedure
EN 61248-6:1997-08	Transformers and inductors for use in electronic and telecommunication equipment Part 6: Sectional specification for inductors on the basis of the capability approval procedure
EN 61248-7:1997-08	Transformers and inductors for use in electronic and telecommunication equipment Part 7: Sectional specification for high-frequency inductors and intermediate frequency transformers on the basis of the capability approval procedure
EN 61249-2-12:1999-04	Materials for printed boards and other interconnecting structures Part 2-12: Sectional specification set for reinforced base materials, clad and unclad - Epoxide non-woven aramid laminate of defined flammability, copper-clad
EN 61249-2-13:1999-04	Materials for printed boards and other interconnecting structures Part 2-13: Sectional specification set for reinforced base materials, clad and unclad - Cyanate ester non-woven aramid laminate of defined flammability, copper clad

EN 61249-2-18:2002-03	Materials for printed boards and other interconnection structures Part 2-18: Reinforced base materials, clad and unclad - Polyester non-woven fibreglass reinforced laminated sheet of defined flammability (vertical burning test), copper-clad
EN 61249-2-19:2002-02	Materials for printed boards and other interconnection structures Part 2-19: Sectional specification set for reinforced base materials, clad and unclad - Epoxide cross-plyed linear fibreglass-reinforced laminated sheet of defined flammability (vertical burning test) copper clad
EN 61249-2-4:2002-03	Materials for printed boards and other interconnecting structures Part 2-4: Reinforced base materials clad and unclad - Polyester non-woven/woven fibreglass laminated sheet of defined flammability (vertical burning test), copper-clad
EN 61249-3-3:1999-04	Materials for printed boards and other interconnecting structures Part 3-3: Sectional specification set for unreinforced base materials, clad and unclad (intended for flexible printed boards) - Adhesive coated flexible polyester film
EN 61249-3-4:1999-04	Materials for printed boards and other interconnecting structures Part 3-4: Sectional specification set for unreinforced base materials, clad and unclad (intended for flexible printed boards) - Adhesive coated flexible polyimide film
EN 61249-3-5:1999-04	Materials for printed boards and other interconnecting structures Part 3-5: Sectional specification set for unreinforced base materials, clad and unclad (intended for flexible printed boards) - Transfer adhesive films
EN 61249-8-8:1997-08	Materials for interconnection structures Part 8: Sectional specification set for non-conductive films and coatings Section 8: Temporary polymer coatings
EN 61332:1997-09	Soft ferrite material classification
EN 61333:1998-04	Marking on U and E ferrite cores
EN 61338-1-3:2000-03	Waveguide type dielectric resonators Part 1-3: General information and test conditions - Measurement method of complex relative permittivity for dielectric resonator materials at microwave frequency
EN 61596:1997-05	Magnetic oxide EP-cores and associated parts for use in inductors and transformers - Dimensions
EN 61605:1997-01	Fixed inductors for use in electronic and telecommunication equipment - Marking codes
EN 61609:1999-02	Microwave ferrite components - Guide for the drafting of specifications
EN 61631:2001-10	Test method for the mechanical strength of cores made of magnetic oxides
EN 61747-2:1999-01	Liquid crystal and solid-state display devices Part 2: Liquid crystal display modules - Sectional specification
EN 61747-2-1:2001-06	Liquid crystal and solid-state display devices Part 2-1: Passive matrix monochrome LCD modules - Blank detail specification
EN 61747-3:1999-09	Liquid crystal and solid state display devices Part 3: Sectional specification for liquid crystal display (LCD) cells
EN 61747-3-1:1999-09	Liquid crystal and solid-state display devices Part 3-1: Liquid crystal display (LCD) cells - Blank detail specification
EN 61747-4:1998-10	Liquid crystal and solid-state display devices Part 4: Liquid crystal display modules and cells - Essential ratings and characteristics
EN 61747-5:1998-09	Liquid crystal and solid-state display devices Part 5: Environmental, endurance and mechanical test methods
EN 61760-2:1998-04	Surface mounting technology Part 2: Transportation and storage conditions of surface mounting devices (SMD) - Application guide
EN 61797-1:1996-12	Transformers and inductors for use in telecommunication and electronic equipment - Main dimensions of coil formers Part 1: Coil formers for laminated cores
EN 61830:1998-02	Microwave ferrite components - Measuring methods for major properties
EN 61837-1:1999-06	Surface mounted piezoelectric devices for frequency control and selection - Standard outlines and terminal lead connections Part 1: Plastic moulded enclosures outlines
EN 61837-2:2000-11	Surface mounted piezoelectric devices for frequency control and selection - Standard outlines and terminal lead connections Part 2: Ceramic enclosures
EN 61837-3:2000-11	Surface mounted piezoelectric devices for frequency control and selection - Standard outlines and terminal lead connections Part 3: Metal enclosures
EN 61843:1997-08	Measuring method for the level of intermodulation products generated in a gyromagnetic device
EN 61860:2000-12	Dimensions of low-profile cores made of magnetic oxides
EN 61943:1999-08	Integrated circuits - Manufacturing line approval application guideline
EN 61964:1999-05	Integrated circuits - Memory devices pin configurations
EN 61965:2003-10	Mechanical safety of cathode ray tubes
EN 61967-1:2002-06	Integrated circuits - Measurement of electromagnetic emissions, 150 kHz to 1 GHz Part 1: General conditions and definitions
EN 61967-4:2002-06	Integrated circuits - Measurement of electromagnetic emissions, 150 KHz to 1 GHz Part 4: Measurement of conducted emissions - 1 ohm/150 ohm direct coupling method
EN 61967-6:2002-10	Integrated circuits - Measurement of electromagnetic emissions, 150 kHz to 1 GHz Part 6: Measurement of conducted emission, magnetic probe method

EN 61988-2-1:2002-12	Plasma display panels Part 2-1: Measuring methods - Optical
EN 62024-1:2002-08	High frequency inductive components - Electrical characteristics and measuring methods Part 1: Nanohenry range chip inductor
EN 62025-1:2002-08	High frequency inductive components - Non-electrical characteristics and measuring methods Part 1: Fixed, surface mounted inductors for use in electronic and telecommunication equipment
EN 62044-1:2002-08	Cores made of soft magnetic materials - Measuring methods Part 1: Generic specification
EN 62044-3:2001-05	Cores made of soft magnetic materials - Measuring methods Part 3: Magnetic properties at high excitation level
EN 62326-4:1997-01	Printed boards Part 4: Rigid multilayer printed boards with interlayer connections -Sectional specification
EN 62326-4-1:1997-01	Printed boards Part 4: Rigid multilayer printed boards with interlayer connections - Sectional specification Section 1: Capability detail specification - Performance levels A, B and C
EN 130200/A3:1998-03 (*)	Sectional Specification: Fixed tantalum capacitors with non-solid or solid electrolyte
EN 130201/A2:1998-03 (*)	Sectional Specification: Fixed tantalum capacitors with solid electrolyte porous anode
EN 130202:1998-03	Blank Detail Specification: Fixed tantalum capacitors with non-solid electrolyte, porous anode (sub-family 2)
EN 130300:1998-03	Sectional Specification: Aluminium electrolytic capacitors with solid and non-solid electrolyte
EN 130500:1998-03	Sectional Specification: Fixed metallized polycarbonate film dielectric capacitors for direct current
EN 130501:1998-03	Blank Detail Specification: Fixed metallized polycarbonate film dielectric capacitors for direct current - Assessment level E
EN 130502:1998-03	Blank Detail Specification: Fixed metallized polycarbonate film dielectric capacitors for direct current - Assessment level EZ
EN 130800:2000-10	Sectional Specification: Tantalum surface mounting capacitors
EN 130800/A1:2003-08	Sectional Specification: Tantalum surface mounting capacitors
EN 131200:2002-05	Sectional Specification: Fixed capacitors with metallized electrodes and polypropylene dielectric
EN 131201:2002-05	Blank Detail Specification: Fixed capacitors with metallized electrodes and polypropylene dielectric
EN 132400/A2:1998-06 (*)	Sectional Specification: Fixed capacitors for electromagnetic interference suppression and connection to the supply mains (Assessment level D)
<i>Per la Norma base cui il presente Amendment si riferisce si veda la CEI EN 132400:1996 (CEI 40-13) nella Sezione "Norme CEI in vigore - Indice progressivo per CT" o nella Sezione "Indice Norme e Pubblicazioni Europee recepite dal CEI"</i>	
EN 132400/A3:1998-10 (*)	Sectional Specification: Fixed capacitors for electromagnetic interference suppression and connection to the supply mains (Assessment level D)
<i>Per la Norma base cui il presente Amendment si riferisce si veda la CEI EN 132400:1996 (CEI 40-13) nella Sezione "Norme CEI in vigore - Indice progressivo per CT" o nella Sezione "Indice Norme e Pubblicazioni Europee recepite dal CEI"</i>	
EN 132400/A4:2001-08 (*)	Sectional Specification: Fixed capacitors for electromagnetic interference suppression and connection to the supply mains (Assessment level D)
<i>Per la Norma base cui il presente Amendment si riferisce si veda la CEI EN 132400:1996 (CEI 40-13) nella Sezione "Norme CEI in vigore - Indice progressivo per CT" o nella Sezione "Indice Norme e Pubblicazioni Europee recepite dal CEI"</i>	
EN 140100/A1:2001-08 (*)	Sectional Specification: Fixed low power non-wire wound resistors
EN 140200/A1:2001-08 (*)	Sectional Specification: Fixed power resistors
EN 140400/A1:2001-08 (*)	Sectional Specification: Fixed low power surface mounting (SMD) resistors
EN 140400/Ec:1997-07 (*)	Sectional Specification: Fixed low power surface mounting (SMD) resistors
EN 140401:2002-05	Blank Detail Specification: Fixed low power non wire-wound surface mounting (SMD) resistors
EN 140401-801:2002-05	Detail Specification: Fixed low power non wire-wound surface mount (SMD) resistors - Rectangular - Stability classes 0,1; 0,25; 0,5; 1
EN 140401-802:2002-05	Detail specification: Fixed low power non wire-wound surface mount (SMD) resistors - Rectangular - Stability classes 1; 2
EN 140401-803:2002-05	Detail specification: Fixed low power non wire-wound surface mount (SMD) resistors - Cylindrical - Stability classes 0,05; 0,1; 0,25; 0,5; 1; 2
EN 140402:1998-08	Blank Detail Specification: Fixed low power wire wound surface mounting (SMD) resistors
EN 153000:1998-04	Generic specification: Discrete pressure contact power semiconductor devices (Qualification approval)
EN 165000-5:1997-12	Film and hybrid integrated circuits Part 5: Procedure for qualification approval
ES 59002:1998-09	General requirements for integrated circuits
ES 59006:1998-11	Methods and draft standards for the dynamic characterization and testing of analog to digital converters (DYNAD)
ES 59008-1:1999-09	Data requirements for semiconductor die Part 1: General requirements
ES 59008-2:1999-09	Data requirements for semiconductor die Part 2: Vocabulary

ES 59008-3:1999-09	Data requirements for semiconductor die Part 3: Mechanical, material and connectivity requirements
ES 59008-4-1:2000-09	Data requirements for semiconductor die Part 4-1: Specific requirements and recommendations - Test and quality
ES 59008-4-2:2000-09	Data requirements for semiconductor die Part 4-2: Specific requirements and recommendations - Handling and storage
ES 59008-4-3:1999-11	Data requirements for semiconductor die Part 4-2: Specific requirements and recommendations - Thermal
ES 59008-4-4:1999-11	Data requirements for semiconductor die Part 4-4: Specific requirements and recommendations - Electrical simulation
ES 59008-5-1:2001-03	Data requirements for semiconductor die Part 5-1: Particular requirements and recommendations for die types - Bare die
ES 59008-5-2:2001-03	Data requirements for semiconductor die Part 5-2: Particular requirements and recommendations for die types - Bare die with added connection structures
ES 59008-5-3:2001-11	Data requirements for semiconductor die Part 5-3: Particular requirements and recommendations for die types - Minimally-packaged die
ES 59008-6-1:1999-09	Data requirements for semiconductor die Part 6-1: Exchange data formats and data dictionary - Data exchange - DDX file format
ES 59008-6-2:2001-03	Data requirements for semiconductor die Part 6-2: Data dictionary
CLC/TC 49	Piezoelectric devices for frequency control and selection (CECC SC) -Sciolto nel 2002
EN 166100:1998-08	Sectional Specification: Surface acoustic wave (SAW) filters
EN 166101:1999-02	Blank Detail Specification: Surface Acoustic Wave (SAW) filters - Capability approval
EN 169000/A1:1998-02 (*)	Generic Specification: Quartz crystal controlled oscillators
EN 170000:1999-09	Generic Specification: Waveguide type dielectric resonators
EN 170100:2001-08	Sectional Specification: Waveguide type dielectric resonators
EN 170101:2001-08	Blank detail Specification: Waveguide type dielectric resonators - Capacity approval
EN 171000:2001-08	Generic specification: Filters using waveguide type dielectric resonators
CLC/SC 51X	Magnetic components: Cores and soft magnetic materials (CECC WG 12A) - Sciolto nel 1998
EN 125000:1997-12	Generic Specification: Cores made of ferrite materials
CLC/BTTF 63-2	Advanced technical ceramics - Sciolto nel 2003
EN 50324-1:2002-05	Piezoelectric properties of ceramic materials and components -- Part 1: Terms and definitions
EN 50324-2:2002-05	Piezoelectric properties of ceramic materials and components Part 2: Methods of measurement - Low power
EN 50324-3:2002-05	Piezoelectric properties of ceramic materials and components Part 3: Methods of measurement - High power
CLC/BTWG 69-2	Compensated connectors for thermo-electric sensors - Sciolto nel 1997
EN 50212:1996-05	Connectors for thermoelectric sensors
CLC/BTTF 95-1	Inspection of electrical installations in domestic accomodations - Sciolto nel 2003
ES 59009:2000-03	Inspection and testing of electrical installations in domestic properties

CLC/BTTF 101-3	Avionic equipment, systems and associated components -Sciolto nel 2002
ES 59010:2001-03	Electronic component policy and management programme Part 1: Avionics requirements
CLC/TC 217	Electronic Design Automation (EDA) - Sciolto nel 2003
R217-020:2001-11	Electronic system specification languages - VHDL modelling guidelines
R217-021:2001-11	Electronic system specification languages - Standard method for building VHDL models of component libraries
EN 61523-1:2002-01	Delay and power calculation standards Part 1: Integrated circuit delay and power calculation systems
EN 61523-2:2002-08	Delay and power calculation standards Part 2: Pre-layout delay calculation specification for CMOS ASIC libraries
EN 61690-1:2000-05	Electronic Design Interchange Format (EDIF) - Version 3.0.0. Level 0 - Information model
EN 61690-2:2000-05	Electronic Design Interchange Format (EDIF) Part 2: Version 4.0.0
EN 61691-1:1997-09	Design automation Part 1: VHDL language reference manual
EN 61691-2:2001-12	Behavioural languages Part 2: VHDL multilogic system for model interoperability
EN 61691-3-2:2001-12	Behavioural languages Part 3-2: Mathematical operation in VHDL
EN 61691-3-3:2001-12	Behavioural languages Part 3-3: IEEE Standard VHDL Synthesis
EN 61926-1:2000-01	Design automation Part 1: Standard test language for all systems Common/abbreviated test language for all systems (C/ATLAS)
EN 62014-1:2002-01	Electronic design automation libraries Part 1: Input/Output buffer information specification (IBIS version 3.2)
ENV 50208-6:1997-06	Data interchange format for Simulated and Measured Data (ISMD)
ENV 50218:1996-02	Description of a parametrized European mini test chip
ENV 50219:1996-02	Description of reliability test structures of the European mini test chip
ENV 50247-1:1998-11	Pinnacles Component Information Standard 1.2 - The PCIS tag library
ENV 50247-2:1998-11	Pinnacles Component Information Standard 1.2 - The SGML declaration and SGML Document Type Definitions (DTDs)
ES 59011:2001-03	Specification for the representation of Quality rules and metrics for Hardware and Software Design Languages
CLC/ WG QAP	
EN 100114-6/A1:1999-02	CECC Quality assessment procedure for electronic components Part 6: Technology approval of manufacturers
IEC/TC 68	Magnetic alloys and steels
EN 60404-2:1998-02	Magnetic materials Part 2: Methods of measurement of the magnetic properties of electrical steel sheet and strip by means of an Epstein frame
EN 60404-4:1997-01	Magnetic materials Part 4: Methods of measurement of d.c. magnetic properties of iron and steel
EN 60404-4/A1:2002-04	Magnetic materials Part 4: Methods of measurement of d.c. magnetic properties of magnetically soft materials
EN 60404-14:2002-10	Magnetic materials Part 14: Methods of measurement of the magnetic dipole moment of a ferromagnetic material specimen by the withdrawal or rotation method

(*) Le presenti Modifiche, emesse dal Comitato per i Componenti Elettronici del CENELEC (CECC), integrano le relative Norme di base di pari numero, a suo tempo adottate come Norme CEI tramite una Dichiarazione di Riconoscimento. Per l'elenco completo delle Norme emesse dal suddetto Comitato si consulti il Catalogo CENELEC in vigore